

Abstract

RESIN COMPOSITION, PREPREG, AND METAL FOIL-CLAD LAMINATE

There are provided a resin composition which has excellent heat resistance, exhibits high optical reflectance in an ultraviolet light region and a visible light region, undergoes less deterioration in optical reflectance when subjected to a heat treatment, and can be used suitably for an LED-mounting printed wiring board; a prepreg containing the resin composition; and a metal foil-clad laminate containing the resin composition, or the like. The resin composition of the present invention contains a fluorene-containing epoxy resin (A) having a specific structure, an acid anhydride (B) of a completely or partially hydrogenated product of an aromatic polycarboxylic acid, titanium dioxide (C), and a wet dispersing agent (D).